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	U	1	I	Document	ID	Title	_Current-08	Current XRef R
	V	L	US	4302268	A	Process for preparing flexible printed-circuit board	156/238	156/249 ; 216/20
	П	С	US	4933042	A	Method for packaging integrated circuit chips employing a polymer film	156/239	156/275.5 ; 156/275.7
				5045141		Method of making solderable printed circuits formed without plating	156/240	156/330 ; 174/257
3			:	5326414		Method for making electrostatic RF absorbant circuit carrier assembly	156/242	156/244.11 ; 156/245
				5468324		Spin-on and peel polymer film method of data recording duplication and	156/247	264/2.1 ; 369/284
9				5749997		Composite bump tape automated bonding method and bonded structure	156/249	156/275.7 ; 156/295
	7	ŗ	US	4701236	A		156/252	156/253 ; 156/261
				5690773		Method for the manufacture of a contact-free or hybrid card	156/267	156/297 ; 156/300
1	:			4765860		Circuit board	156/272.6	156/274.8 ; 156/307.3
1						Method for mounting electronic parts	156/273.5	156/275.5 ; 156/275.7
1	- 1		:			Connection construction and method of manufacturing the same	156/273.9	156/325 ; 438/119
	:					Additive process for producing printed circuit elements using a	156/280	156/230 ; 156/249
	- 1					Lamination process	156/302	156/351 ; 156/358
F	- 1			4662973		Continuous process for preparing reinforced resin laminates	156/307.4	156/247 ; 156/313
	****		US	5296074	A	Method for bonding small electronic components	156/309.9	156/312

